

Customer Information Notification

202301032 | : MC10XS4200 Data Sheet Update Rev 9.0 (Technical Clarifications / Corrections)

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 12, 2023 Effective date: Aug 13, 2023

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Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrica spec./Test coverage
[]Firmware	[X]Other: Da / Corrections	ta Sheet Update (Technical C	larifications	

PCN Overview

Description

NXP Semiconductors announces the data sheet update to revision 9.0 for the MC10XS4200 high-side switch devices associated with this notification.

Please see the revision history included in the updated document for a detailed description of the changes.

New MC10XS4200 revision 9.0 data sheet is attached to this notification, and can be accessed at NXP.com: https://www.nxp.com/docs/en/data-sheet/MC10XS4200.pdf

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The data sheet has been updated for technical clarifications and corrections.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Eva Li

Position Applications Engineering

e-mail

address jing-ampd.li@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
MC10XS4200BFK	934070604557	MC10XS4200BFK	SPD10 phaseII	HPwrQFN23	SOT1938-1	DOD	No	BLC3
MC10XS4200BFKR2	934070604578	MC10XS4200BFKR2	SPD10 phaseII	HPwrQFN23	SOT1938-1	DOD	No	BLC3
MC10XS4200BAFK	934070607557	MC10XS4200BAFK	SPD10 phaseII	HPwrQFN23	SOT1938-1	DOD	No	BLC3
MC10XS4200BAFKR2	934070607578	MC10XS4200BAFKR2	SPD10 phaseII	HPwrQFN23	SOT1938-1	DOD	No	BLC3
MC10XS4200DFK	934072415557	MC10XS4200DFK	SPD10 PHASEII ICN8	HPwrQFN23	SOT1938-1	RFS	No	BLC3
MC10XS4200DFKR2	934072415578	MC10XS4200DFKR2	SPD10 PHASEII ICN8	HPwrQFN23	SOT1938-1	RFS	No	BLC3
MC10XS4200BDFK	934072413557	MC10XS4200BDFK	SPD10 Trim config ICN8	HPwrQFN23	SOT1938-1	RFS	No	BLC3
MC10XS4200BDFKR2	934072413578	MC10XS4200BDFKR2	SPD10 Trim config ICN8	HPwrQFN23	SOT1938-1	RFS	No	BLC3